DuPont™ PlasmaSolv® EKC245™

Post-Etch Residue Remover

DuPont™ PlasmaSolv® EKC245™ post-etch residue remover is made with DuPont™ HDA® hydroxylamine technology for enhanced performance.

**Features**
- High purity specifications for advanced wafer cleaning
- Removes residues from vias
- Cleans HBr etched polysilicon
- Removes residues after metal etch
- Operates below flashpoint
- Low evaporation rate at operating temperatures
- Does not require ultrasonics
- Rinses in water
- Compatible with automatic equipment
- Great device reliability and product yields
- Lowers via contact resistance
- Maintains gate oxide integrity
- Improves contact between metal layers
- Combines wet chemical processes
- Provides a safe chemical process
- Extends bath life, reduces air emissions, lowers factory operating cost
- Reduces equipment requirements
- Reduces cost of ownership by simplifying process
- Offers flexibility in process

**0.5 µm Metal Lines**
- Before Clean
- After Clean—Ox/Ti/AlCu/TiN 20 min at 65 °C

**0.5 µm Via**
- Before Clean
- After Clean—AlSiCu/TiN/TEOS 20 min at 65 °C
For more information on DuPont™ PlasmaSolv® EKC245™ or other DuPont products, please visit our website.

The information provided in this data sheet corresponds to our knowledge on the subject at the date of its publication. It may be subject to revision as new knowledge and experience becomes available. This information is not intended to substitute for any testing you may need to conduct to determine for yourself the suitability of our products for your particular purposes. Since we cannot anticipate all variations in end-use and disposal conditions, DuPont makes no warranties and assumes no liability in connection with any use of this information. It is intended for use by persons having technical skill, at their own discretion and risk. Nothing in this publication is to be considered as a license to operate under or a recommendation to infringe any patent right.

CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see “DuPont Medical Caution Statement,” H-50102-S and “DuPont Policy Regarding Medical Applications” H-50103-S.

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